

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Yong Wook Shin	11/26/2007
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	DONGBU HITEK CO., LTD.
<b>Street Address:</b>	891-10 Daechi-dong, Gangnam-gu
<b>City:</b>	Seoul
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12573837
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(801)328-1707
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
<b>Phone:</b>	(801) 533-9800
<b>Email:</b>	kclark@wnlaw.com
<b>Correspondent Name:</b>	Eric L. Maschoff
<b>Address Line 1:</b>	WORKMAN NYDEGGER
<b>Address Line 2:</b>	60 East South Temple, Suite 1000
<b>Address Line 4:</b>	Salt Lake City, UTAH 84111
<b>ATTORNEY DOCKET NUMBER:</b>	17323.14.1
<b>NAME OF SUBMITTER:</b>	ERIC L. MASCHOFF
<b>Total Attachments: 2</b>	
source=17323-14-1-Assignment#page1.tif	
source=17323-14-1-Assignment#page2.tif	

OP \$40.00 12573837

WHEN RECORDED RETURN TO:

PATENT APPLICATION  
Docket No. 17323.14

Workman Nydegger  
1000 Eagle Gate Tower  
60 East South Temple  
Salt Lake City, Utah 84111

---

ASSIGNMENT

---

I/We the undersigned, hereinafter collectively referred to as "Assignor", have made an invention entitled SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING SEMICONDUCTOR DEVICE. Preferred embodiments of said invention are disclosed in a United States patent application which:

- is executed concurrently herewith for filing in the United States Patent and Trademark Office.
- was previously filed in the United States Patent and Trademark Office on December 6, 2007 Application Serial No. 11/951,846.
- is a United States National Application of PCT International Application No. \_\_\_\_\_, filed \_\_\_\_\_.

(The attorneys of Workman Nydegger are hereby authorized to insert the serial number and filing date when known.)

The Assignee, DONGBU HITEK CO., LTD., having a principal place of business at 891-10 Daechi-dong, Gangnam-gu, Seoul, Korea, desires to secure the entire right, title and interest in said invention and the patent application filed thereon.

In consideration of One Dollar (\$1.00) and other good and valuable consideration paid to Assignor by the Assignee, the receipt and sufficiency of which is hereby acknowledge, ASSIGNOR HEREBY ASSIGNS TO THE ASSIGNEE:

The entire right, title, and interest in the above-identified United States patent application and in all divisions, continuations and continuations-in-part of said application, or reissues or extensions of letters patent or patents granted thereon, and in all patents issuing thereon in the United States.

ASSIGNMENT  
Attorney Docket No. 17323.14  
Page 1 of 2

The right to claim the benefit of any prior related United States or foreign patent applications.

Assignor hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all patents on said invention to the Assignee as the owner of the entire interest, for the sole use and behoof of the said Assignee, its successors, assigns and legal representatives.

Assignor hereby agrees, without further consideration and without expense to Assignor, to sign all lawful papers and to perform all other lawful acts which the Assignee may request of Assignor to make this Assignment fully effective, including, by way of example but not of limitation, the following:

Prompt execution of all original, divisional, substitute, reissue, and other United States applications and all lawful documents requested by the Assignee to further the prosecution of any of such patent applications.

Cooperation to the best of Assignor's ability in the execution of all lawful documents, the production of evidence, nullification, reissue, extension, or infringement proceedings involving said application.

This assignment and agreement shall be binding upon Assignor's heirs and legal representatives.

**Inventor 1**

Yong Wook \_\_\_\_\_ SHIN \_\_\_\_\_  
(GIVEN NAME) (MIDDLE INITIAL OR NAME) FAMILY (OR LAST NAME)  
Inventor's signature 신용욱 Date 11/26, 2007